

ABSTRACT OF THE DISCLOSURE

TACKY FILM FRAME FOR ELECTRONIC DEVICE STORAGE

A device for storing and transporting electronic devices such as semiconductor chips, comprising: a frame having a top side, a bottom side, a periphery, and a window within the periphery, a thin film covering the window, the thin film having on its top surface an adhesive layer, the adhesive layer being adapted to hold a plurality of electronic devices, the electronic devices being attachable to the adhesive layer at any location on the thin film within the window, and the electronic devices being uncovered, a recess in the bottom side, and a raised flange around the window on the top side wherein the raised flange of one of the devices mates with the recess of another device, thereby allowing the devices to be stacked. The adhesive properties of the adhesive layer may be greatly reduced by exposure to electromagnetic radiation such as heat (infrared) or ultraviolet, thereby releasing the electronic device.

Fig. 6